



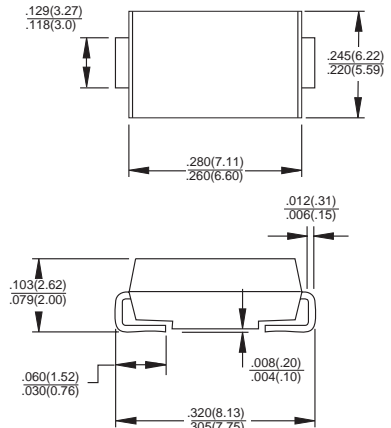
Features

- ✧ For surface mounted application
- ✧ Metal to silicon rectifier, majority carrier conduction
- ✧ Low forward voltage drop
- ✧ Easy pick and place
- ✧ High surge current capability
- ✧ Epitaxial construction
- ✧ High temperature soldering:
260°C / 10 seconds at terminals

Mechanical Data

- ✧ Case: Molded plastic
- ✧ Terminals: Solder plated
- ✧ Polarity: Indicated by cathode band
- ✧ Weight: 0.21 gram

SMC/DO-214AB



Dimensions in inches and (millimeters)

Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60 Hz, resistive or inductive load.

For capacitive load, derate current by 20%

Type Number	Symbol	SK 32	SK 33	SK 34	SK 35	SK 36	SK 39	SK 310	Units	
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	20	30	40	50	60	90	100	V	
Maximum RMS Voltage	V_{RMS}	14	21	28	35	42	63	70	V	
Maximum DC Blocking Voltage	V_{DC}	20	30	40	50	60	90	100	V	
Maximum Average Forward Rectified Current at T_A (See Fig. 1)	$I_{(AV)}$	3.0							A	
Peak Forward Surge Current, 8.3 ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	100							A	
Maximum Instantaneous Forward Voltage (Note 1) @ 3.0A	V_F	0.5			0.75		0.85		V	
Maximum DC Reverse Current @ $T_A = 25^\circ\text{C}$ at Rated DC Blocking Voltage @ $T_A = 100^\circ\text{C}$	I_R	0.5					0.6			mA
		20			10.0		20			mA
Typical Thermal Resistance (Note 2)	$R_{\theta_{JL}}$	17							$^\circ\text{C}/\text{W}$	
	$R_{\theta_{JA}}$	55							$^\circ\text{C}/\text{W}$	
Operating Temperature Range	T_J	-55 to +125				-55 to +150				$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55 to +150								$^\circ\text{C}$

Notes: 1. Pulse Test with PW=300 usec, 1% Duty Cycle

2. Measured on P.C.Board with 0.6 x 0.6"(16 x 16mm) Copper Pad Areas.

FIG.1- MAXIMUM FORWARD CURRENT DERATING CURVE

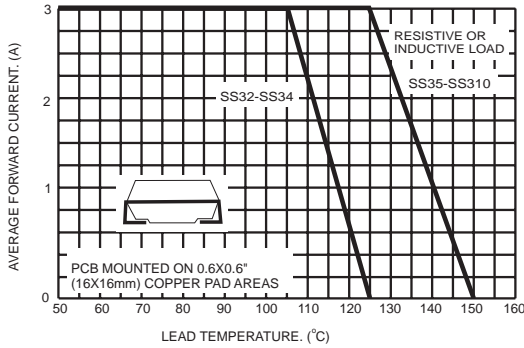


FIG.2- MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

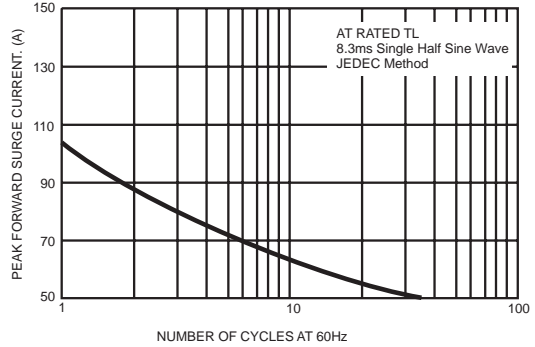


FIG.3- TYPICAL FORWARD CHARACTERISTICS

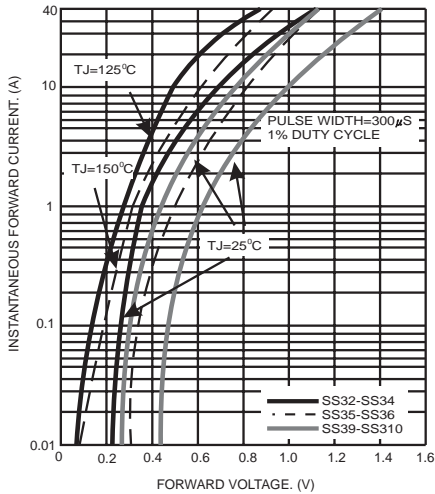


FIG.4- TYPICAL REVERSE CHARACTERISTICS

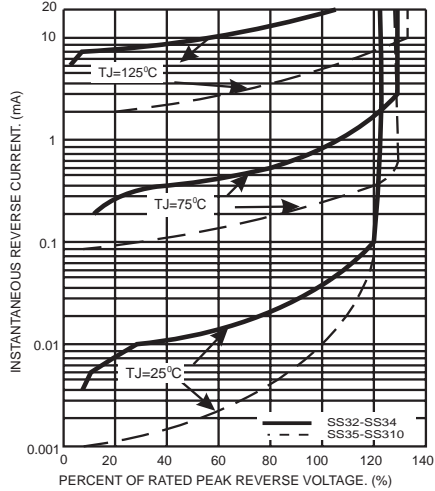


FIG.5- TYPICAL JUNCTION CAPACITANCE

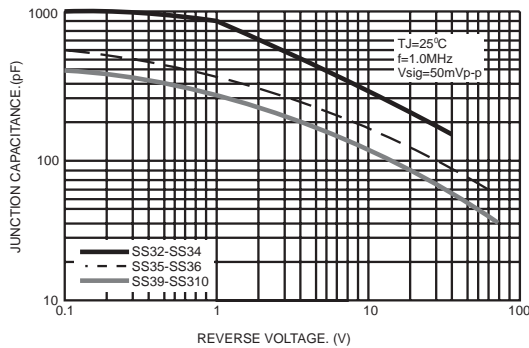


FIG.6- TYPICAL TRANSIENT THERMAL IMPEDANCE

